1 2 3 4 5 6	SLATER HERSEY & LIEBERMAN LLE A Limited Liability Partnership MARK K. SLATER, Cal. Bar No. 12974 mslater@slaterhersey.com JONATHAN P. HERSEY, Cal. Bar No. 2 jhersey@slaterhersey.com SCOTT B. LIEBERMAN, Cal. Bar No. 2 slieberman@slaterhersey.com 3950 Civic Center Dr., Suite 300 San Rafael, California 94903 Telephone: 415-294-7700 Facsimile: 949-398-7501	20RIGINAL FILED NOV 3 0 2012 Richard W. Wieking Clerk, U.S. District Court Northern District of California San Jose
8	Attorneys for Plaintiff SANDISK CORPORATION	
9	UNITED STATES DISTRICT COURT	
10	NORTHERN DISTRICT OF CALIFORNIA	
11	(SAN JOSE DIVISION) PSG	
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13	SANDISK CORPORATION, a Delaware corporation,	$V_{as}V_{as} = 06081$
14	Plaintiff,	COMPLAINT FOR BREACH OF
15	v.	CONTRACT
16 17	ZURICH AMERICAN INSURANCE COMPANY, a New York corporation,	DEMAND FOR JURY TRIAL
18	Defendant.	
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		COMPLAINT

COMPLAINT

7. SanDisk is a global leader in flash memory storage solutions. Its flash memory technology is integrated into mobile, computing, and consumer electronics products from top electronics companies and sold at approximately 250,000 international retail outlets.

8. SanDisk manufactures its memory products at world-class manufacturing facilities that produce more than two million products each day. In a joint venture with Toshiba, SanDisk operates some of the largest, most advanced manufacturing facilities in the world that are used to make NAND flash memory chips. These include the fabrication facilities, or "fabs," in Yokkaichi, Japan, known as "FAB 3" and "FAB 4." FAB 3 opened in 2005 and FAB4 opened in 2007. Each fab houses thousands of sophisticated tools, each being an integral part of a state-of-the-art production process.

9. The fabrication process at these fabs is a highly specialized, integrated process during which electronic circuits are gradually created on a silicon wafer. The wafers are transported in pods along a track to each step in the production process in clean room environments. An Automatic Material Handling System ("AMHS") directs the pods through the process using a system of controllers, and each step is recorded and tracked. A photolithographic "printing" process is used to build a chip layer by layer. Many layers are deposited across a wafer and then removed in small areas to create transistors and interconnects. Together they will form the active "on/off" part of the chip's circuitry plus the connections between them, in a three-dimensional structure. The process is performed dozens of time on each wafer, with hundreds or thousands of chips placed grid-like on a wafer and processed simultaneously. After creating layers on the wafers, the wafers are sorted and tested to ensure that chip circuits meet specifications. The finished wafers are

-3-

then cut with a diamond saw, separating the microprocessors, and each functioning die is assembled into a package that protects the die. This package delivers the power and electrical connections when placed on a computer circuit board or other device such as a cell phone. The entire fabrication process for a given batch from start to a finished product takes approximately twelve weeks.

The Insurance Policy

- 10. On or about April 1, 2010, SanDisk and Zurich entered into The Zurich Edge–Global insurance contract, known as Policy No. PPR5966360-02 (the "Policy"). The Policy period extended from April 1, 2010 through April 1, 2011. The policy limit is \$500,000,000. The annual policy premium paid by SanDisk was \$2,239,259.
- 11. The Policy provided in pertinent part coverage for "direct physical loss of or damage caused by" a Covered Cause of Loss to Covered Property, as defined by the Policy, as well as for business interruption.

The Accidental Power Loss and Shut-Down of FABs 3 & 4

- 12. On December 8, 2010, at approximately 5:20 a.m., a loss of power occurred at FABs 3 & 4 in Yokkaichi, Japan. SanDisk is informed and believes that the power drop was due to the failure of a transformer unit at the Yokkaichi Power Plant, which provides electricity to FABs 3 & 4. The power drop lasted 7/10s of one second or 158 milliseconds.
- 13. The sudden drop in electrical power affected approximately 100% of the tools in FAB 3 and 80% of the tools in FAB 4, for a total of approximately 3,300 tools. As a result, the highly integrated production system was disrupted and production declined significantly.

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- Following the power drop, repairs and remedial steps were necessary to 14. resume full production. The repairs and remedial steps included a variety of servicing from internal and external equipment experts. These measures included, but were not limited to, parts replacement, physical adjustments, recalibration, and requalification. Repairs and remedial steps continued for approximately four days. Due to the 12-week manufacturing cycle and the integrated nature of the systems, production declines continued through at least the end of February 2011.
- 15. The Automated Material Handling System (the "AMHS"), which controls the movement of the wafers, was also interrupted and was unable to perform its intended functions without remedial measures. The AMHS, through the use of controllers, records the state of each lot at all times and directs the transport of the wafers in pods along a track to and from specialized cabinets called stockers and to and from the manufacturing tools. Due to the interruption, the AMHS could not properly perform these functions, and a "cold start" had to be performed. In FAB 3, all wafers had to be relocated to the stockers and scanned to determine the correct location. It took approximately 28 hours in FAB 3 to scan and reload all the wafers.
- As a result of the sudden drop in electricity, approximately 8,600 16. wafers that would have been available to SanDisk were scrapped.
- 17. At certain phases of the manufacturing process wafers must be processed within a defined time period or else they will be scrapped. In order to minimize scrap, the production priorities were shifted resulting in slowed production. As a result, SanDisk was unable to produce 36,000 wafers compared to SanDisk's share of the expected FAB output had the power drop not occurred.

- 18. As a result of receiving fewer wafers from the FABs, SanDisk was unable to sell the expected level of product to its customers and lost profits from sales and incurred other losses, including, but not limited to, costs involved with reprogramming, restoring, servicing, and requalifying the highly sophisticated tools, in an amount to be determined, but in excess of \$63,485,912, excluding the applicable deductible.
- 19. The losses SanDisk suffered as a result of the system outages were within the coverage provided by the Zurich Edge-Global Policy, including without limitation, the provisions providing coverage at Section I (Insuring Agreement), Section IV (Time Element), Section V (Special Coverages and Described Causes of Loss), and Section VII(12) (Covered Cause of Loss).
- 20. On or around December 12, 2010, SanDisk, through its broker, Integro Insurance Group, informed Zurich of the circumstances related to the power loss.
- 21. On or around September 17, 2012, Zurich, in breach of its obligations under the policy, denied SanDisk's claim and informed SanDisk that, except for \$102,719 provided as Professional Fees coverage, the majority of the losses SanDisk suffered as a result of the interruption to its business were not covered by its policy and denied payment to SanDisk.
- 22. SanDisk has performed each and every term and condition required of SanDisk under the Policy.
- 23. As an actual and legal result of Zurich's breach of contract, SanDisk has suffered damages in an amount to be proven at trial, but in excess of \$63,485,912, less the applicable deductible.

1 PRAYER FOR RELIEF 2 WHEREFORE, Plaintiff SanDisk prays for judgment as follows: 3 That judgment be entered against defendant Zurich for SanDisk's 4 1. actual damages as a result of Zurich's breach of the Policy; 5 6 7 That SanDisk recover its Investigative Costs incurred establishing the 2. 8 existence and exact amount of its claim, according to proof; 9 That SanDisk be granted pre-judgment and post-judgment interest on 10 3. these amounts: 11 12 13 4. That SanDisk recover its attorneys' fees as permitted by law, equity or 14 contract; 15 16 5. That SanDisk recover its costs of this suit; and 17 18 6. That SanDisk be granted such other and further relief as the Court 19 deems just and proper. 20 Dated: November 29, 2012 21 22 SLATER HERSEY & LIEBERMANDLE 23 24 ByMARK K. SLATER 25 26 Attorneys for Plaintiff SANDISK CORPORATION 27

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DEMAND FOR JURY TRIAL

Plaintiff SanDisk Corporation hereby demands trial by jury pursuant to Rule 38(b) of the Federal Rules of Civil Procedure.

Dated: November 29, 2012

SLATER HERSEY & LIEBERMAN LLP

Ву

MARK/K. SLATER

Attorneys for Plaintiff SANDISK CORPORATION

-8-

SLATER HERSEY & LIEBERMA A Limited Liability Partnership ORIGINAL FILED MARK K. SLATER, Cal. Bar No. 129742 mslater@slaterhersey.com 3 JONATHAN P. HERSEY, Cal. Bar No. 189240 ihersey@slaterhersey.com SCOTT B. LIEBERMAN, Cal. Bar No. 208764 slieberman@slaterhersey.com Richard W. Wieking Northern District of Court San Inca California 3950 Civic Center Dr., Suite 300 E. San Rafael, California 94903 Telephone: 415-294-7700 949-398-7501 Facsimile: Attorneys for Plaintiff 8 SANDISK CORPORATION 9 UNITED STATES DISTRICT COURT 10 NORTHERN DISTRICT OF CALIFORNIA (SAN JOSE DIVISION) 11 12 ₩selv2 - 06081PSG SANDISK CORPORATION, a 13 Delaware corporation, 14 Plaintiff, CERTIFICATION OF 15 ERESTED ENTITIES OR PERSONS PURSUANT TO 16 FEDERAL RULE OF CIVIL ZURICH AMERICAN INSURANCE PROCEDURE 7.1 AND 17 COMPANY, a New York corporation, NORTHERN DISTRICT LOCAL **RULE 3-16** Defendant. 18 19 20 21 22 23 24 25 26 27 28

CERTIFICATION OF INTERESTED PARTIES

1	This Certification as to Interested Entities or Persons is filed pursuant to	
2	Federal Rule of Civil Procedure 7.1 and Northern District of California Local Rule	
3	3-16.	
4		
5	Pursuant to Fed. R. Civ. P. 7.1, Plaintiff SanDisk Corporation ("SanDisk")	
6	certifies that it does not have a parent corporation, and no publicly held corporation	
7	owns 10% or more of its stock.	
8		
9	Pursuant to Civil L.R. 3-16, the undersigned certifies that as of this date, other	
10	than the named parties, there is no such interest to report.	
11		
12	These representations are made to enable the Court to evaluate possible	
13	disqualification or recusal.	
14		
15	Dated: November 29, 2012	
16	SLATER HERSEY & LIEBERMAN LLP	
17		
18	By	
19	MARK K. SLATER	
20	Attorneys for Plaintiff	
21	SANDISK CORPORATION	
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CERTIFICATION OF INTERESTED PARTIES